

Abstract of the Disclosure:

A reaction chamber for processing a substrate wafer is described. The reaction chamber has a wafer holder for receiving the substrate wafer, a convection plate, which is disposed above the wafer holder, for suppressing convective movements over the substrate wafer, and a gas distributor plate which is disposed on a side face of the reaction chamber, for distributing process or purge gases that flow in. A flow plate is disposed on the gas distributor plate and extends substantially in a plane that is perpendicular to the gas distributor plate. This allows rapid and efficient purging of the reaction chamber.

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